



January 2015

FJBE2150D

ESBC™ Rated NPN Silicon Transistor

ESBC Features (FDC655 MOSFET)

| $V_{CS(ON)}$ | I_C | Equiv. $R_{CS(ON)}$ |
|--------------|-------|----------------------|
| 0.131 V | 0.5 A | $0.261 \Omega^{(1)}$ |

- Low Equivalent On Resistance
- Very Fast Switch: 150 kHz
- Squared RBSOA: Up to 1500 V
- Avalanche Rated
- Low Driving Capacitance, No Miller Capacitance (Typ. 12 pF Capacitance at 200 V)
- Low Switching Losses
- Reliable HV Switch: No False Triggering due to High dv/dt Transients

Applications

- High-Voltage and High-Speed Power Switches
- Emitter-Switched Bipolar/MOSFET Cascode (ESBC™)
- Smart Meters, Smart Breakers, HV Industrial Power Supplies
- Motor Drivers and Ignition Drivers

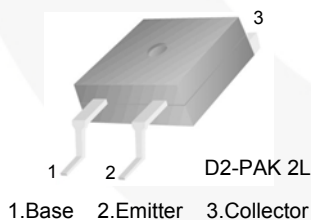


Figure 1. Pin Configuration

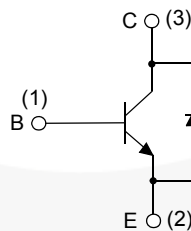


Figure 2. Internal Schematic Diagram

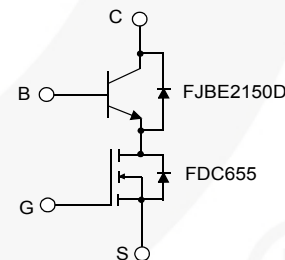


Figure 3. ESBC Configuration⁽²⁾

Description

The FJBE2150D is a low-cost, high-performance power switch designed to be used in an ESBC™ configuration in applications such as: power supplies, motor drivers, smart grid, or ignition switches. The power switch is designed to operate up to 1500 volts and up to 3 amps, while providing exceptionally low on-resistance and very low switching losses.

The ESBC™ switch is designed to be driven using off-the-shelf power supply controllers or drivers. The ESBC™ MOSFET is a low-voltage, low-cost, surface-mount device that combines low-input capacitance and fast switching. The ESBC™ configuration further minimizes the required driving power because it does not have Miller capacitance.

The FJBE2150D provides exceptional reliability and a large operating range due to its square Reverse-Bias-Safe-Operating-Area (RBSOA) and rugged design. The device is avalanche rated and has no parasitic transistors, so is not prone to static dv/dt failures.

The power switch is manufactured using a dedicated high-voltage bipolar process and is packaged in high-voltage HV-D2PAK rated at 2500 V creepage and clearance.

Ordering Information

| Part Number | Marking | Package | Packing Method |
|-------------|---------|-----------------------|----------------|
| FJBE2150DTU | J2150D | D2-PAK 2L (TO-263 2L) | Tube |

Notes:

1. Figure of Merit.
2. Other Fairchild MOSFETs can be used in this ESBC application.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Value | Unit |
|-----------|---|--------------|------------------|
| V_{CBO} | Collector-Base Voltage | 1500 | V |
| V_{CEO} | Collector-Emitter Voltage | 800 | V |
| V_{EBO} | Emitter-Base Voltage | 12 | V |
| I_C | Collector Current | 2 | A |
| I_{CP} | Collector Current (Pulse) | 3 | A |
| I_B | Base Current | 1 | A |
| I_{BP} | Base Current (Pulse) | 2 | A |
| P_D | Power Dissipation ($T_C = 25^\circ\text{C}$) | 110 | W |
| T_J | Operating and Junction Temperature Range | - 55 to +125 | $^\circ\text{C}$ |
| T_{STG} | Storage Temperature Range | - 65 to +150 | $^\circ\text{C}$ |
| EAS | Avalanche Energy ($T_J = 25^\circ\text{C}$, 8 mH) | 3.5 | mJ |

Thermal Characteristics⁽³⁾

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Max. | Unit |
|-----------------|---|-------|--------------------|
| $R_{\theta jc}$ | Thermal Resistance, Junction to Case | 1.13 | $^\circ\text{C/W}$ |
| $R_{\theta ja}$ | Thermal Resistance, Junction to Ambient | 76.42 | $^\circ\text{C/W}$ |

Note:

- Device mounted on FR-4 PCB, board size = 76.2 mm x 114.3 mm, land pattern 12.70 mm x 9.45 mm, trace size = 10 mil.

Electrical Characteristics⁽⁴⁾Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------|--------------------------------------|--|------|------|------|---------------|
| BV_{CBO} | Collector-Base Breakdown Voltage | $I_C = 0.5\text{ mA}, I_E = 0$ | 1500 | 1689 | | V |
| BV_{CEO} | Collector-Emitter Breakdown Voltage | $I_C = 5\text{ mA}, I_B = 0$ | 800 | 870 | | V |
| BV_{EBO} | Emitter-Base Breakdown Voltage | $I_E = 0.5\text{ mA}, I_C = 0$ | 12.0 | 14.8 | | V |
| I_{CES} | Collector Cut-off Current | $V_{CES} = 1500\text{ V}, I_E = 0$ | | 0.01 | 100 | μA |
| I_{CEO} | Collector Cut-off Current | $V_{CE} = 800\text{ V}, V_{BE} = 0$ | | 0.01 | 100 | μA |
| I_{EBO} | Emitter Cut-off Current | $V_{EB} = 12\text{ V}, I_C = 0$ | | 0.05 | 500 | μA |
| h_{FE} | DC Current Gain | $V_{CE} = 3\text{ V}, I_C = 0.4\text{ A}$ | 20 | 29 | 35 | |
| | | $V_{CE} = 10\text{ V}, I_C = 5\text{ mA}$ | 20 | 43 | | |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | $I_C = 0.25\text{ A}, I_B = 0.05\text{ A}$ | | 0.16 | | V |
| | | $I_C = 0.5\text{ A}, I_B = 0.167\text{ A}$ | | 0.12 | | |
| | | $I_C = 1\text{ A}, I_B = 0.33\text{ A}$ | | 0.25 | | |
| $V_{BE(sat)}$ | Base-Emitter Saturation Voltage | $I_C = 500\text{ mA}, I_B = 50\text{ mA}$ | | 0.74 | 1.20 | V |
| | | $I_C = 2\text{ A}, I_B = 0.4\text{ A}$ | | 0.85 | 1.20 | |
| C_{IB} | Input Capacitance | $V_{EB} = 10\text{ V}, I_C = 0, f = 1\text{ MHz}$ | | 745 | 1000 | pF |
| C_{OB} | Output Capacitance | $V_{CB} = 200\text{ V}, I_E = 0, f = 1\text{ MHz}$ | | 15 | | pF |
| f_T | Current Gain Bandwidth Product | $I_C = 0.1\text{ A}, V_{CE} = 10\text{ V}$ | | 5 | | MHz |
| V_F | Diode Forward Voltage | $I_F = 0.4\text{ A}$ | | 0.76 | 1.20 | V |
| | | $I_F = 1\text{ A}$ | | 0.83 | 1.50 | |

Note:4. Pulse test: pulse width = 20 μs , duty cycles $\leq 10\%$.

ESBC Configured Electrical Characteristics⁽⁵⁾

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------|--|--|------|-------|------|------------|
| f_T | Current Gain Bandwidth Product | $I_C = 0.1\text{ A}, V_{CE} = 10\text{ V}$ | | 25 | | MHz |
| t_f | Inductive Current Fall Time | $V_{GS} = 10\text{ V}, R_G = 47\ \Omega,$ $V_{Clamp} = 500\text{ V},$ $t_p = 3.1\ \mu\text{s}, I_C = 0.3\text{ A},$ $I_B = 0.03\text{ A}, L_C = 1\text{ mH},$ $SRF = 480\text{ kHz}$ | | 137 | | ns |
| t_s | Inductive Storage Time | | | 350 | | ns |
| V_{t_f} | Inductive Voltage Fall Time | | | 120 | | ns |
| V_{t_r} | Inductive Voltage Rise Time | | | 100 | | ns |
| t_c | Inductive Crossover Time | | | 137 | | ns |
| t_f | Inductive Current Fall Time | $V_{GS} = 10\text{ V}, R_G = 47\ \Omega,$ $V_{Clamp} = 500\text{ V},$ $t_p = 10\ \mu\text{s}, I_C = 1\text{ A},$ $I_B = 0.2\text{ A}, L_C = 1\text{ mH},$ $SRF = 480\text{ kHz}$ | | 35 | | ns |
| t_s | Inductive Storage Time | | | 980 | | ns |
| V_{t_f} | Inductive Voltage Fall Time | | | 30 | | ns |
| V_{t_r} | Inductive Voltage Rise Time | | | 195 | | ns |
| t_c | Inductive Crossover Time | | | 210 | | ns |
| V_{CSW} | Maximum Collector Source Voltage at Turn-off without Snubber | $h_{FE} = 5, I_C = 2\text{ A}$ | 1500 | | | V |
| $I_{GS(OS)}$ | Gate-Source Leakage Current | $V_{GS} = \pm 20\text{ V}$ | | 1.0 | | nA |
| $V_{CS(ON)}$ | Collector-Source On Voltage | $V_{GS} = 10\text{ V}, I_C = 2\text{ A}, I_B = 0.67\text{ A}, h_{FE} = 3$ | | 2.210 | | V |
| | | $V_{GS} = 10\text{ V}, I_C = 1\text{ A}, I_B = 0.33\text{ A}, h_{FE} = 3$ | | 0.321 | | |
| | | $V_{GS} = 10\text{ V}, I_C = 0.5\text{ A}, I_B = 0.17\text{ A}, h_{FE} = 3$ | | 0.131 | | |
| | | $V_{GS} = 10\text{ V}, I_C = 0.3\text{ A}, I_B = 0.06\text{ A}, h_{FE} = 5$ | | 0.166 | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{BS} = V_{GS}, I_B = 250\ \mu\text{A}$ | | 1.9 | | V |
| C_{iss} | Input Capacitance ($V_{GS} = V_{CB} = 0$) | $V_{CS} = 25\text{ V}, f = 1\text{ MHz}$ | | 470 | | pF |
| $Q_{GS(tot)}$ | Gate-Source Charge $V_{CB} = 0$ | $V_{GS} = 10\text{ V}, I_C = 8\text{ A}, V_{CS} = 25\text{ V}$ | | 9 | | nC |
| $r_{DS(ON)}$ | Static Drain-Source On Resistance | $V_{GS} = 10\text{ V}, I_D = 6.3\text{ A}$ | | 21 | | m Ω |
| | | $V_{GS} = 4.5\text{ V}, I_D = 5.5\text{ A}$ | | 26 | | |
| | | $V_{GS} = 10\text{ V}, I_D = 6.3\text{ A}, T_J = 125^\circ\text{C}$ | | 30 | | |

Note:

5. Used typical FDC655 MOSFET values in table. Values can vary if other Fairchild MOSFETs are used.

Typical Performance Characteristics

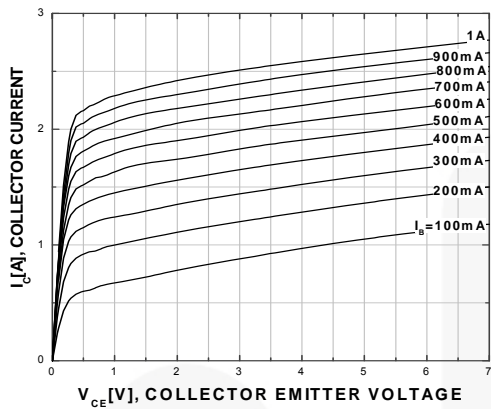


Figure 4. Static Characteristic

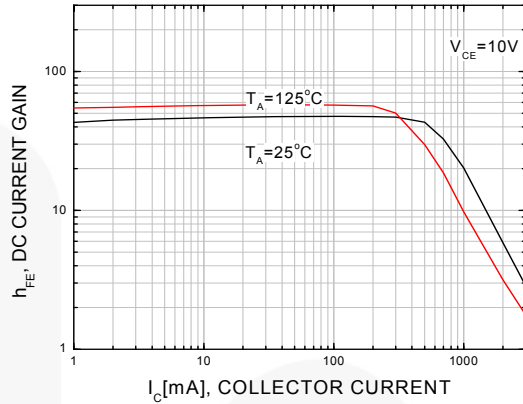


Figure 5. DC Current Gain

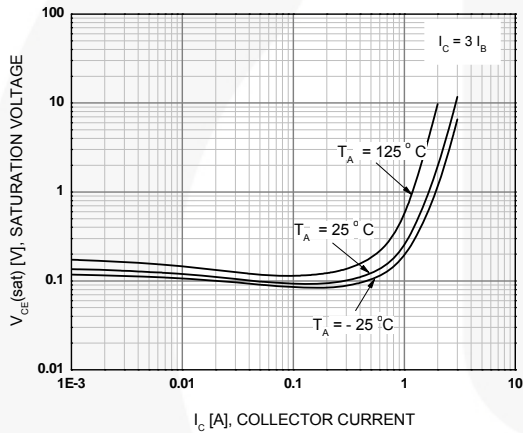


Figure 6. Collector-Emitter Saturation Voltage
 $h_{FE} = 3$

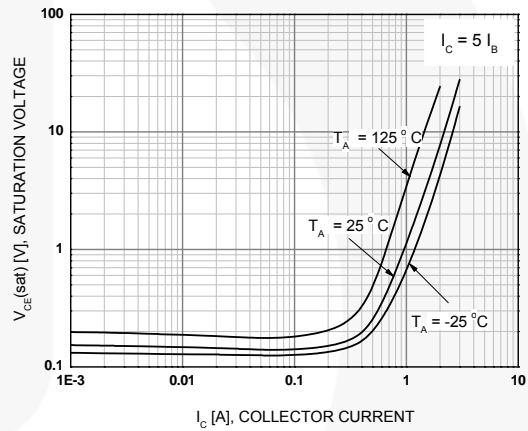


Figure 7. Collector-Emitter Saturation Voltage
 $h_{FE} = 5$

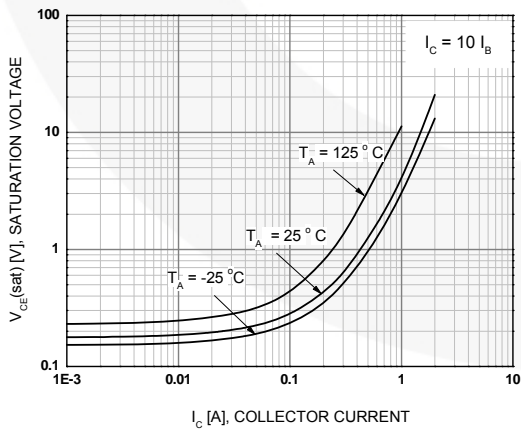


Figure 8. Collector-Emitter Saturation Voltage
 $h_{FE} = 10$

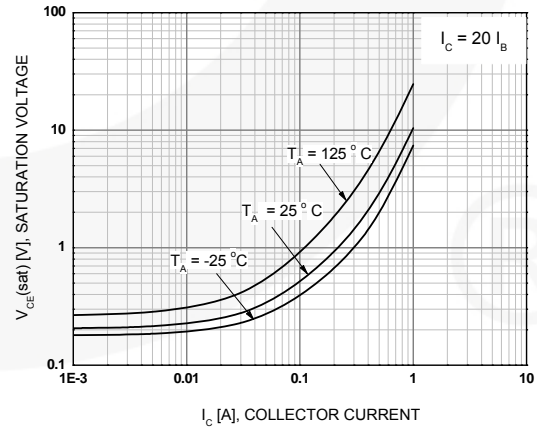


Figure 9. Collector-Emitter Saturation Voltage
 $h_{FE} = 20$

Typical Performance Characteristics (Continued)

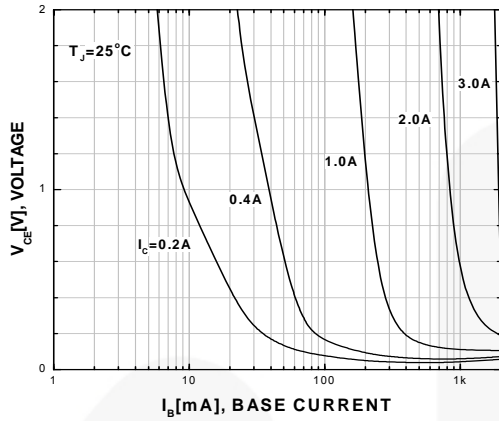


Figure 10. Typical Collector Saturation Voltage

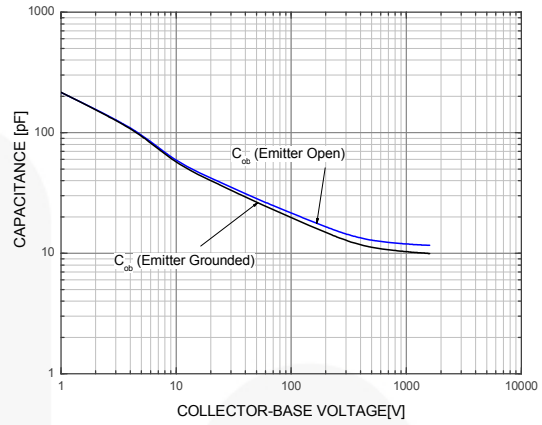


Figure 11. Capacitance

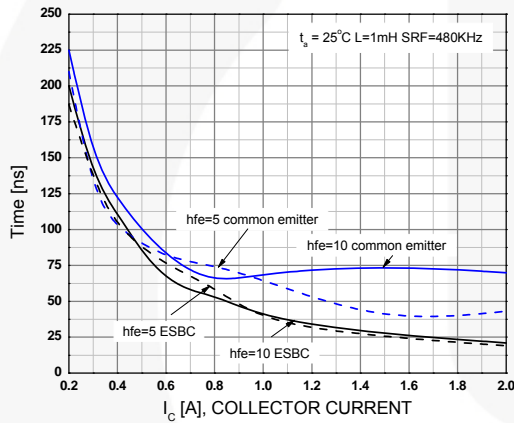


Figure 12. Inductive Load Collector Current Fall-Time (t_f)

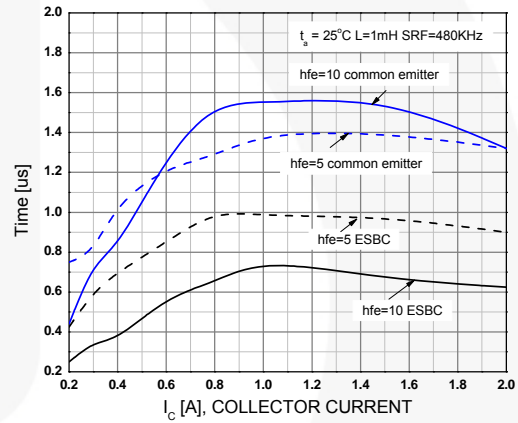


Figure 13. Inductive Load Collector Current Storage Time (t_{stg})

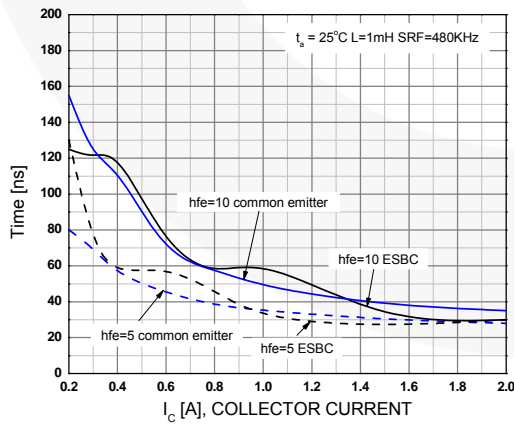


Figure 14. Inductive Load Collector Voltage Fall-Time (t_f)

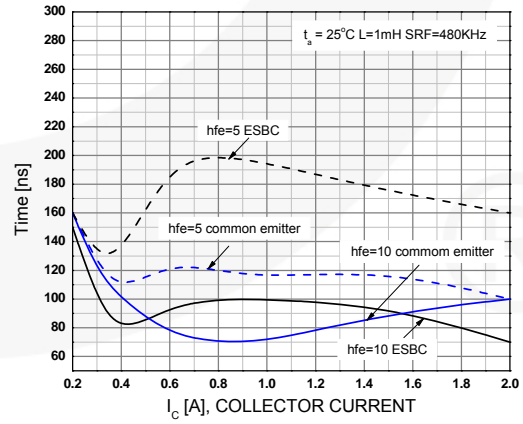


Figure 15. Inductive Load Collector Voltage Rise-Time (t_r)

Typical Performance Characteristics (Continued)

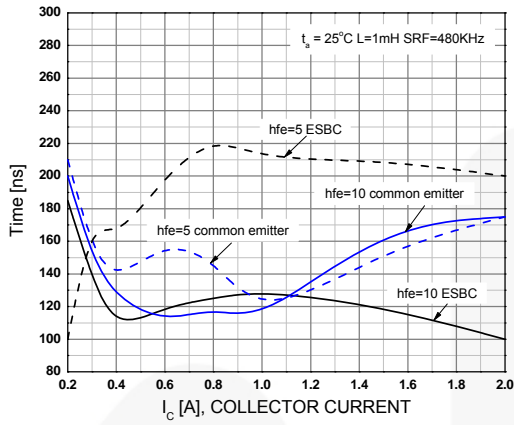


Figure 16. Inductive Load Collector Current / Voltage Crossover (t_c)

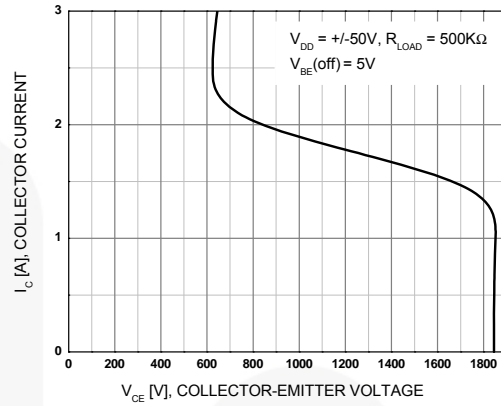


Figure 17. BJT Reverse Bias Safe Operating Area

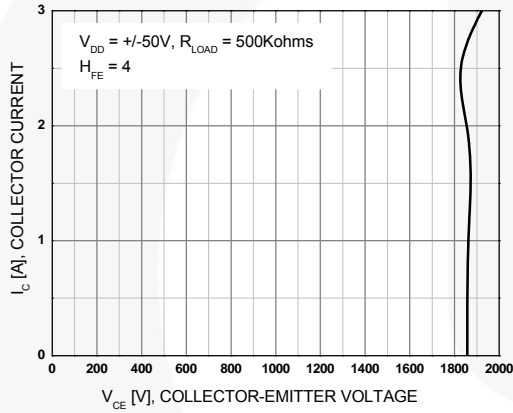


Figure 18. ESBC RBSOA

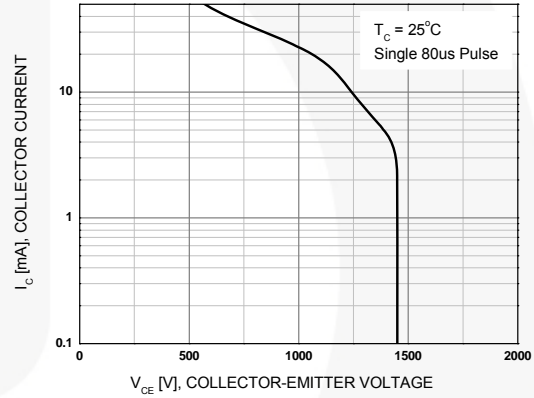


Figure 19. Crossover Forward Bias Safe Operating Area (FBSOA)

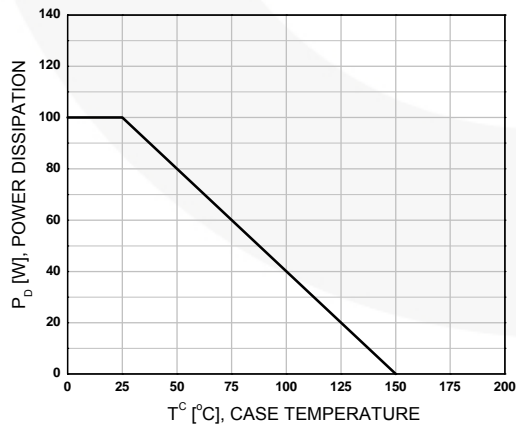


Figure 20. Power Derating

Test Circuits

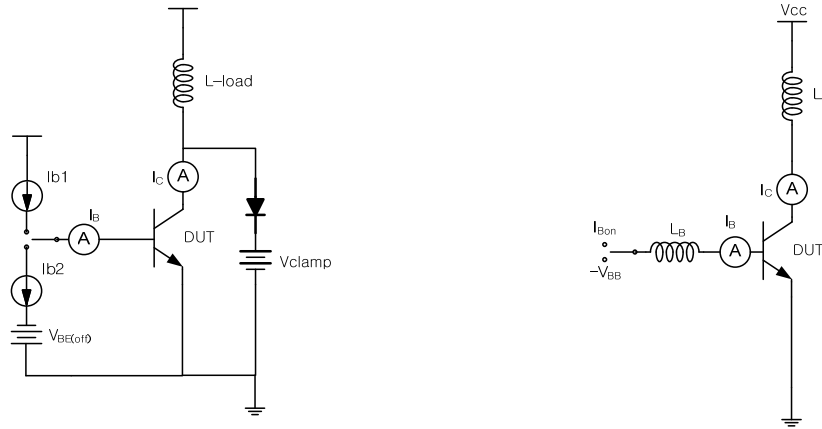


Figure 21. Test Circuit for Inductive Load and Reverse Bias Safe Operating

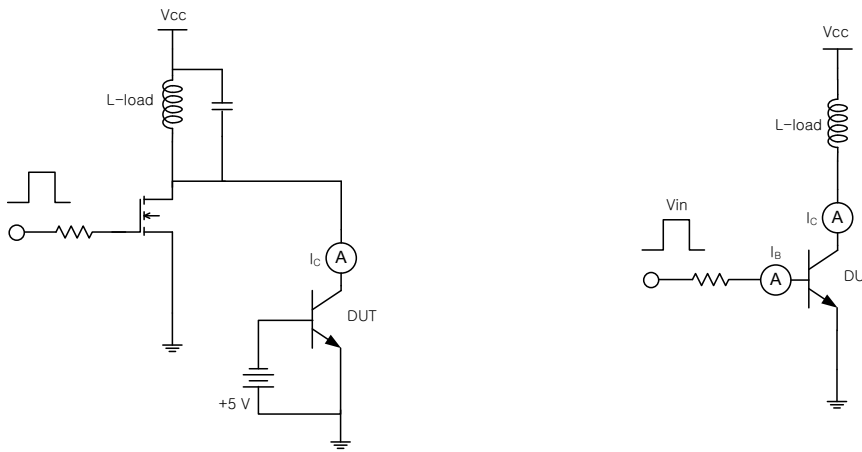


Figure 22. Energy Rating Test Circuit

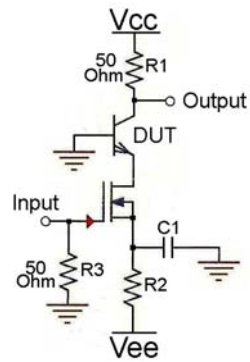


Figure 23. f_T Measurement

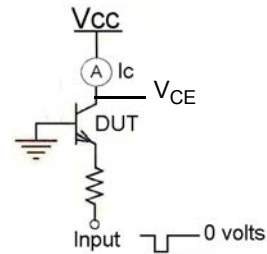


Figure 24. FBSOA

Functional Test Waveforms (Continued)

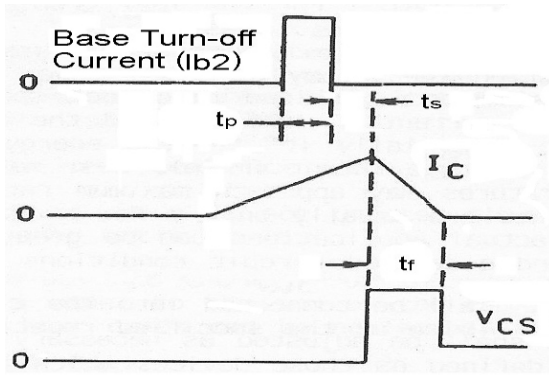


Figure 28. Storage Time - Common Emitter Base Turn-off (I_{b2}) to I_C Fall-Time

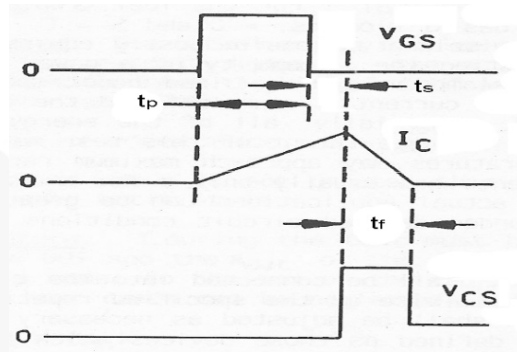
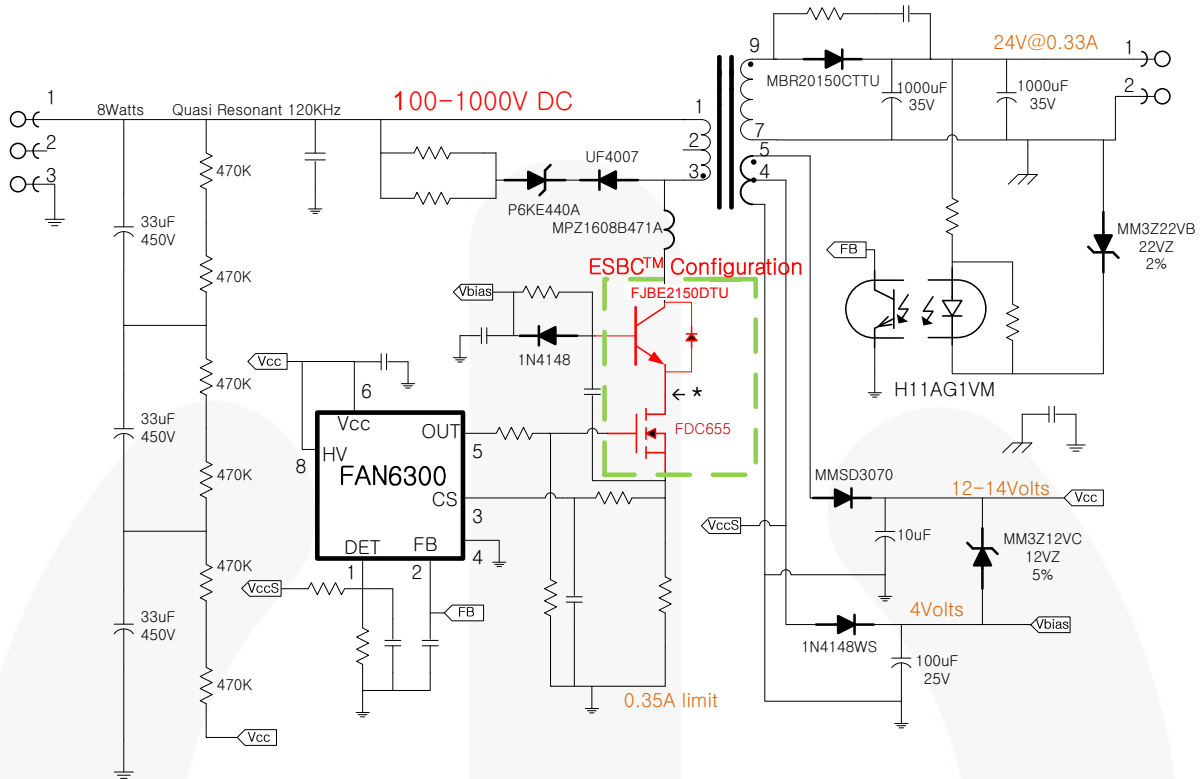


Figure 29. Storage Time - ESBC FET Gate (off) to I_C Fall-Time



Very Wide Input Voltage Range Supply



* Make short as possible

Figure 30. 8 W; Secondary-Side Regulation: 3 Capacitor Input; Quasi Resonant

Driving ESBC Switches

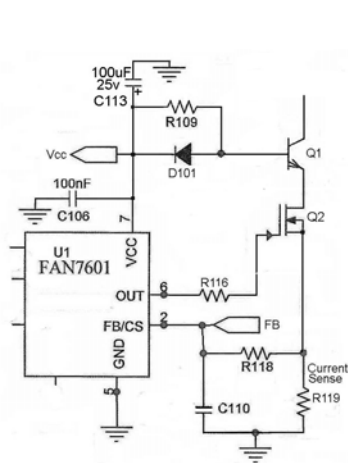


Figure 31. V_{CC} Derived

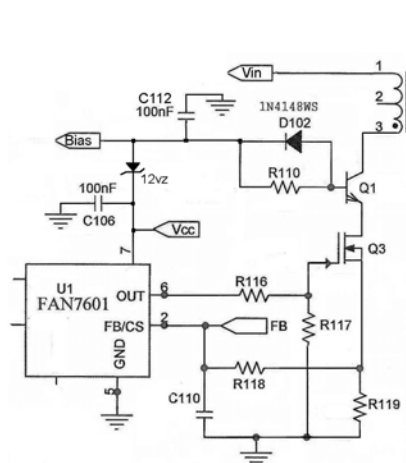


Figure 32. V_{bias} Supply Derived

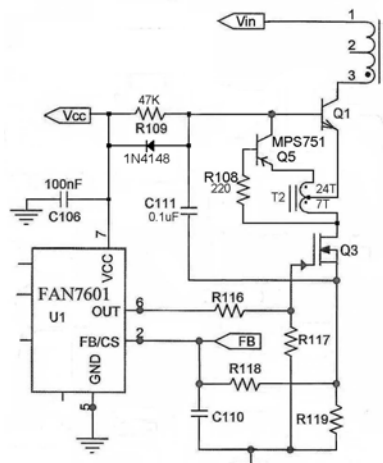


Figure 33. Proportional Drive

Physical Dimensions

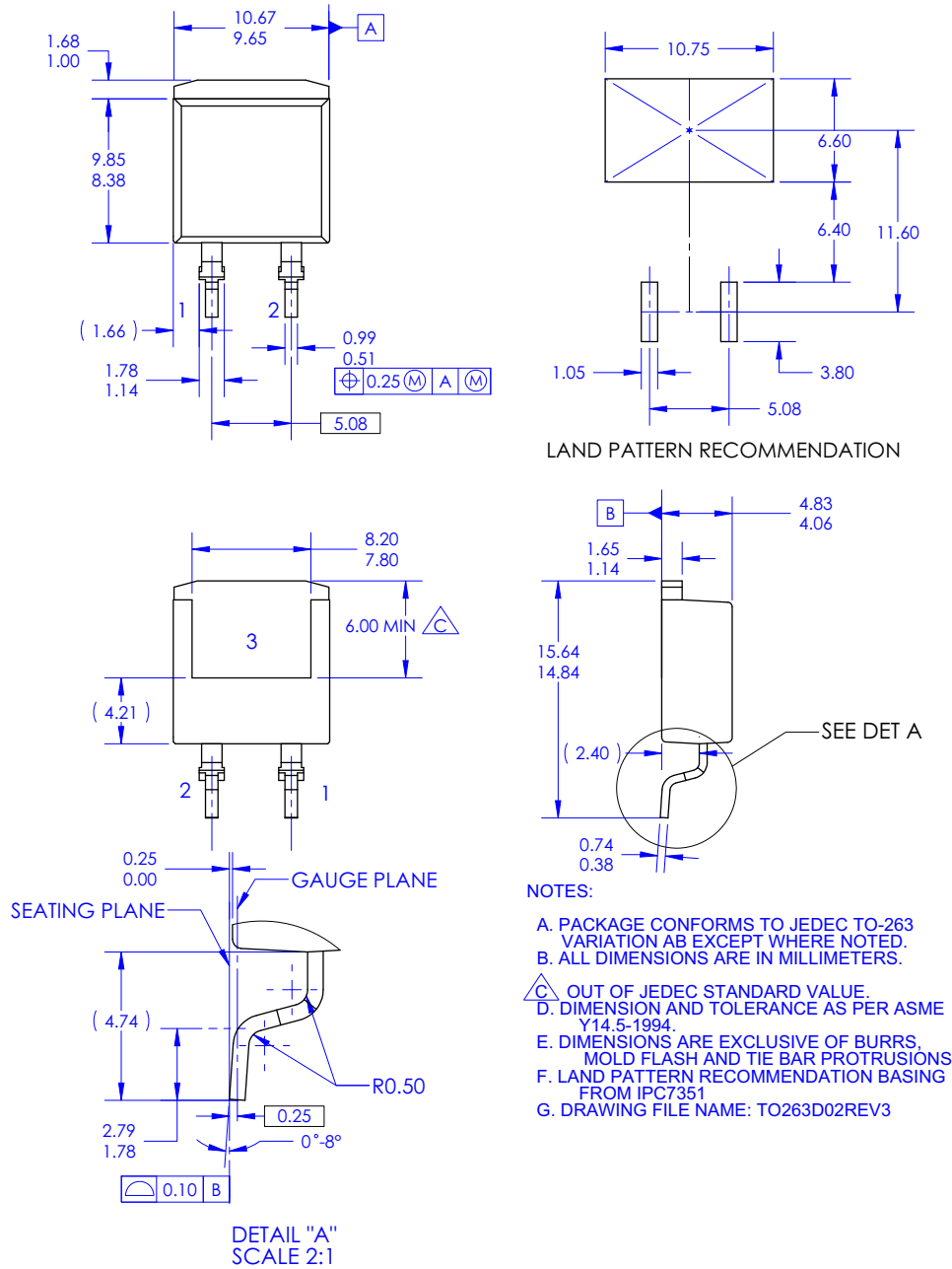







Figure 34. 2 LEAD, TO-263, JEDEC TO263 VARIATION AB, D2PAK



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| No Identification Needed | Full Production | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design. |
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Rev. I73